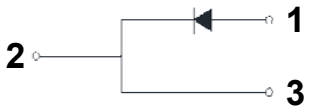
HC1D02065A

Silicon Carbide Schottky Diode

General Description

This product family offers state of the art performance. It is designed for high frequency applications where high efficiency and high reliability are required.

TO-220H-2L



Features

- Low conduction loss due to low V_F
- Extremely low switching loss by tiny Q_C
- Highly rugged due to better surge current
- Industrial standard quality and reliability

Applications

- UPS
- Power Inverter
- High performance SMPS
- Power factor correction

Ordering Part Number	Package	Marking
HC1D02065A	TO-220H-2L	HC1D02065A

Maximum Ratings (at Tc = 25 °C, unless otherwise specified)

Parameter	Symbol	Value	Unit
Repetitive Peak Reverse Voltage	V_{RRM}	650	V
Surge Peak Reverse Voltage	V_{RSM}	650	V
DC Peak Reverse Voltage	V_R	650	V
Continuous Forward Current T_C = 25°C T_C = 135°C T_C = 162°C	I_F	 8 4 2	A
Repetitive Peak Forward Surge Current T_C = 25°C,t_p=10ms,Half Sine Pulse T_C = 110°C,t_p=10ms,Half Sine Pulse	I_{FRM}	 12 8	A
Non-Repetitive Forward Surge Current T_C = 25°C,t_p=10ms,Half Sine Pulse T_C = 110°C,t_p=10ms,Half Sine Pulse	I_{FSM}	 18 14	A
i^2dt value T_C = 25°C,t_p=10ms,Half Sine Pulse T_C = 110°C,t_p=10ms,Half Sine Pulse	$\int i^2dt$	 1.62 0.98	A^2s
Power dissipation T_C = 25°C T_C = 110°C	P_{tot}	 37.5 16	W
Operating junction Range	T_j	-55 to +175	°C
Storage temperature Range	T_{stg}	-55 to +150	°C

Thermal Resistance

Parameter	Symbol	Typ.	Unit
Thermal resistance, junction – case.	$R_{thJC(TYP)}$	3.0	°C/W

Electrical Characteristic (at Tc = 25 °C, unless otherwise specified)

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Forward Voltage	V_F	-	1.3	1.5	V	I_F=2A, T_j=25°C
		-	1.5			T_j=175°C
Reverse Current	I_R	-	10	50	μA	V_R=650V, T_j=25°C
		-	40	150		T_j=175°C
Total Capacitive Charge	Q_C	-	3.7	-	nC	V_R=400V, T_j=25℃ $Q_C = \int_0^{V_R} C(V)dV$
Total Capacitance	C	-	181	-	pF	T_j=25℃, f=1MHz, V_R=0V
		-	10	-		V_R=200V
		-	8	-		V_R=400V

Characteristics Curve

Fig 1: Forward Characteristics

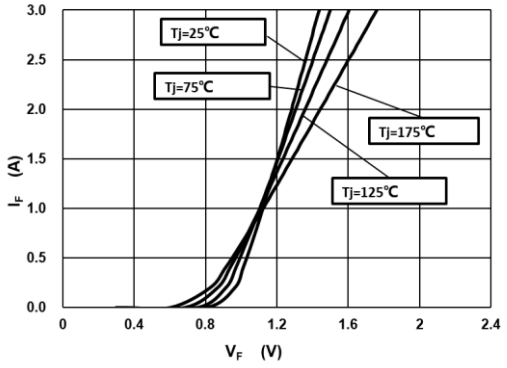


Fig 2: Reverse Characteristics

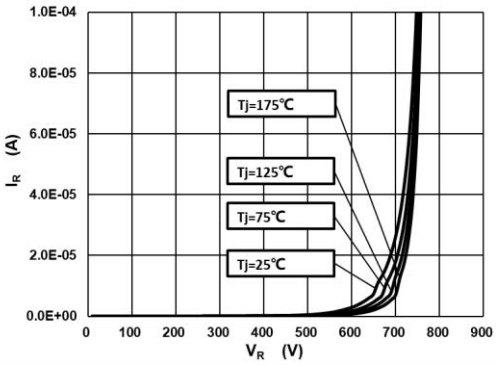


Fig 3: Current Derating

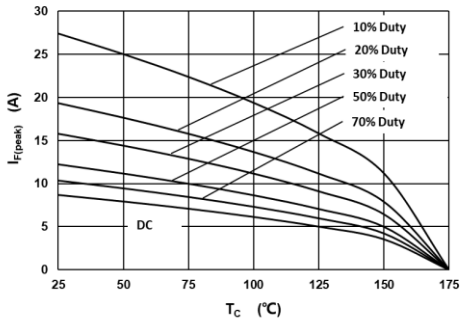


Fig 4: Power Derating

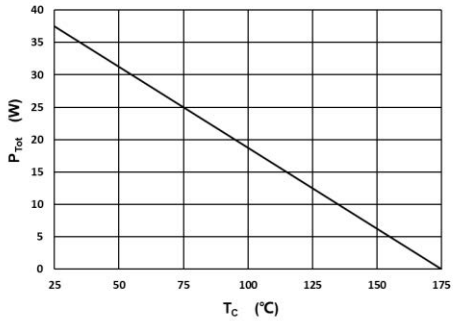


Fig 5: Capacitance vs. Reverse Voltage

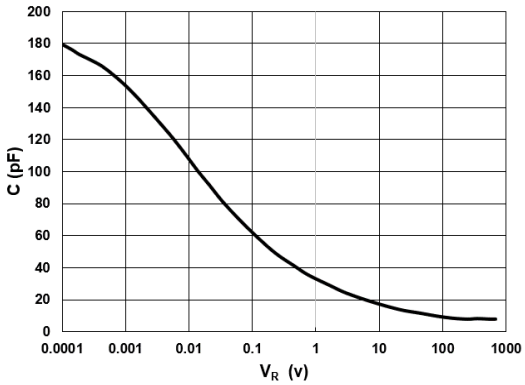


Fig 6: Reverse Charge vs. Reverse Voltage

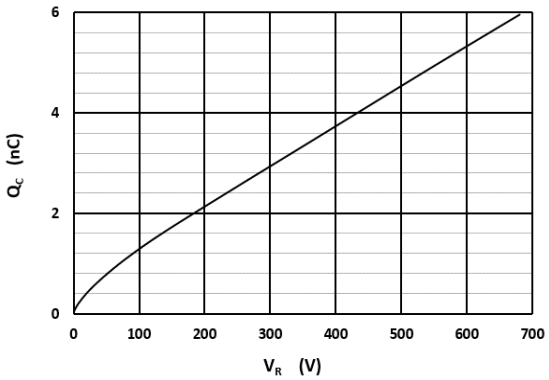


Fig 7: Typical Capacitance Stored Energy

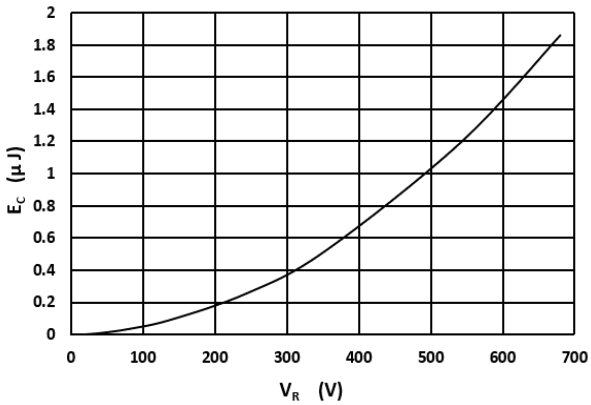
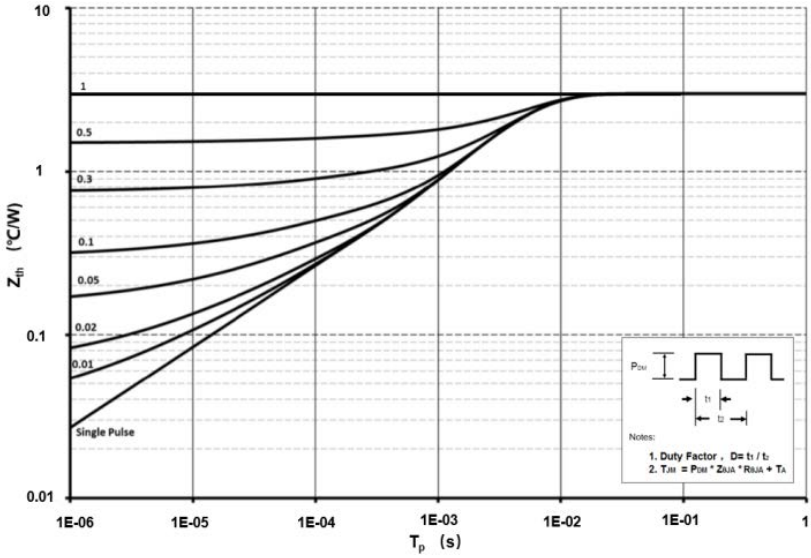
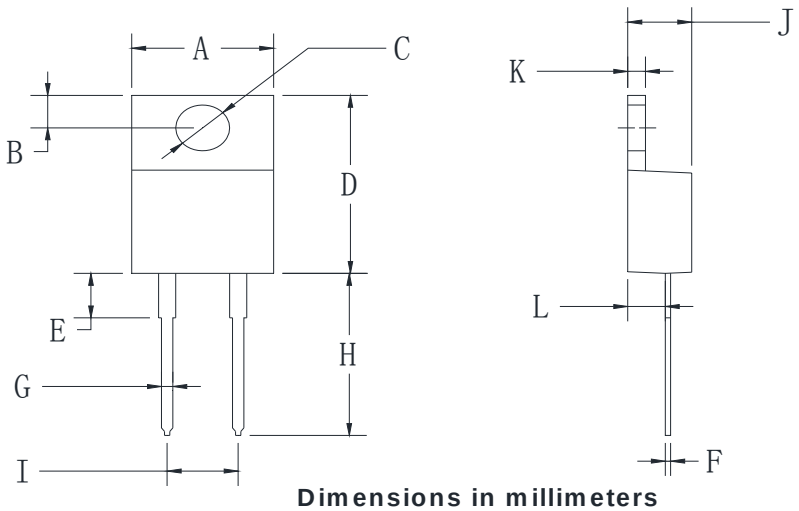


Fig 8: Transient Thermal Impandance



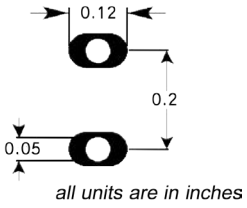
Package Information
TO-220H-2L



Dimensions in millimeters

TO-220H-2L		
Dim	Min	Max
A	9.5	10.9
B	2.22	3.27
C	3.34	4.31
D	14.5	15.5
E	3.16	4.46
F	0.28	0.64
G	0.68	0.94
H	13.06	14.62
I	4.55	5.60
J	4.04	5.1
K	1.14	1.4
L	2.14	3.19

Recommended Solder Pad Layout



all units are in inches

TO-220H-2L

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